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Si4421 Universal ISM Band FSK Transceiver

DESCRIPTION

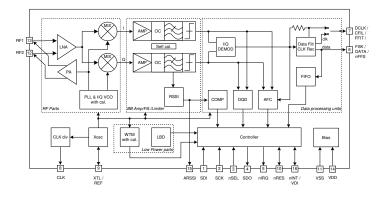
Silicon Labs' Si4421 is a single chip, low power, multi-channel FSK transceiver designed for use in applications requiring FCC or ETSI conformance for unlicensed use in the 433, 868 and 915 MHz bands. The Si4421 transceiver is a part of Silicon Labs' EZRadio™ product line, which produces a flexible, low cost, and highly integrated solution that does not require production alignments. The chip is a complete analog RF and baseband transceiver including a multi-band PLL synthesizer with PA, LNA, I/Q down converter mixers, baseband filters and amplifiers, and an I/Q demodulator. All required RF functions are integrated. Only an external crystal and bypass filtering are needed for operation.

The Si4421 features a completely integrated PLL for easy RF design, and its rapid settling time allows for fast frequency-hopping, bypassing multipath fading and interference to achieve robust wireless links. The PLL's high resolution allows the usage of multiple channels in any of the bands. The receiver baseband bandwidth (BW) is programmable to accommodate various deviation, data rate and crystal tolerance requirements. The transceiver employs the Zero-IF approach with I/Q demodulation. Consequently, no external components (except crystal and decoupling) are needed in most applications.

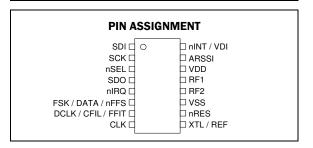
The Si4421 dramatically reduces the load on the microcontroller with the integrated digital data processing features: data filtering, clock recovery, data pattern recognition, integrated FIFO and TX data register. The automatic frequency control (AFC) feature allows the use of a low accuracy (low cost) crystal. To minimize the system cost, the Si4421 can provide a clock signal for the microcontroller, avoiding the need for two crystals.

For low power applications, the Si4421 supports low duty cycle operation based on the internal wake-up timer.

FUNCTIONAL BLOCK DIAGRAM



Si4421



This document refers to Si4421-IC rev A1.

See www.silabs.com/integration for any applicable errata. See back page for ordering information.

FEATURES

- Fully integrated (low BOM, easy design-in)
- No alignment required in production
- Fast-settling, programmable, high-resolution PLL synthesizer
- Fast frequency-hopping capability
- High bit rate (up to 115.2 kbps in digital mode and 256 kbps in analog mode)
- · Direct differential antenna input/output
- Integrated power amplifier
- Programmable TX frequency deviation (15 to 240 kHz)
- Programmable RX baseband bandwidth (67 to 400 kHz)
- · Analog and digital RSSI outputs
- Automatic frequency control (AFC)
- Data quality detection (DQD)
- Internal data filtering and clock recovery
- RX synchron pattern recognition
- · SPI compatible serial control interface
- Clock and reset signals for microcontroller
- 16-bit RX Data FIFO
- Two 8-bit TX data registers
- Low power duty cycle mode
- Standard 10 MHz crystal reference with on-chip tuning
- Wake-up timer
- 2.2 to 3.8 V supply voltage
- Low power consumption
- Low standby current (0.3 μA)
- Compact 16 pin TSSOP package
- Supports very short packets (down to 3 bytes)
- Excellent temperature stability of the RF parameters
- Good adjacent channel rejection/blocking

TYPICAL APPLICATIONS

- Home security and alarm
- · Remote control, keyless entry
- Wireless keyboard/mouse and other PC peripherals
- Toy controls
- · Remote keyless entry
- Tire pressure monitoring
- Telemetry
- Personal/patient data logging
- Remote automatic meter reading



Si4421-DS rev 2.4r 0708 www.silabs.com



DETAILED FEATURE-LEVEL DESCRIPTION

The Si4421 FSK transceiver is designed to cover the unlicensed frequency bands at 433, 868 and 915 MHz. The device facilitates compliance with FCC and ETSI requirements.

The receiver block employs the Zero-IF approach with I/Q demodulation, allowing the use of a minimal number of external components in a typical application. The Si4421 incorporates a fully integrated multi-band PLL synthesizer, PA with antenna tuning, an LNA with switchable gain, I/Q down converter mixers, baseband filters and amplifiers, and an I/Q demodulator followed by a data filter.

PLL

The programmable PLL synthesizer determines the operating frequency, while preserving accuracy based on the on-chip crystal-controlled reference oscillator. The PLL's high resolution allows the usage of multiple channels in any of the bands.

RF Power Amplifier (PA)

The power amplifier has an open-collector differential output and can directly drive different PCB antennas with a programmable output power level. An automatic antenna tuning circuit is built in to avoid costly trimming procedures and the so-called "hand effect".

LNA

The LNA has approximately 250 Ohm input impedance, which functions well with the proposed antennas (see: Application Notes available from www.silabs.com/integration)

If the RF input of the chip is connected to 50 Ohm devices, an external matching circuit is required to provide the correct matching and to minimize the noise figure of the receiver.

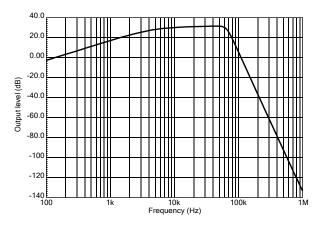
The LNA gain can be selected in four steps (between 0 and -20dB relative to the highest gain) according to RF signal strength. It can be useful in an environment with strong interferers.

Baseband Filters

The receiver bandwidth is selectable by programming the bandwidth (BW) of the baseband filters. This allows setting up the receiver according to the characteristics of the signal to be received.

An appropriate bandwidth can be chosen to accommodate various FSK deviation, data rate and crystal tolerance requirements. The filter structure is 7^{th} order Butterworth low-pass with 40 dB suppression at $2 \cdot$ BW frequency. Offset cancellation is done by using a high-pass filter with a cut-off frequency below 7 kHz.

Full Baseband Amplifier Transfer Function BW=67kHz



Data Filtering and Clock Recovery

Output data filtering can be completed by an external capacitor or by using digital filtering according to the final application.

Analog operation: The filter is an RC type low-pass filter followed by a Schmitt-trigger (St). The resistor (10 kOhm) and the St are integrated on the chip. An (external) capacitor can be chosen according to the actual bit rate. In this mode, the receiver can handle up to 256 kbps data rate. The FIFO cannot be used in this mode and clock is not provided for the demodulated data.

Digital operation: A digital filter is used with a clock frequency at 29 times the bit rate. In this mode, there is a clock recovery circuit (CR), which can provide synchronized clock to the data. Using this clock the received data can fill a FIFO. The CR has three operation modes: fast, slow, and automatic. In slow mode, its noise immunity is very high, but it has slower settling time and requires more accurate data timing than in fast mode. In automatic mode, the CR automatically changes between fast and slow mode. The CR starts in fast mode, then after locking, it automatically switches to slow mode

(Only the digital data filter and the clock recovery use the bit rate clock. For analog operation, there is no need for setting the correct bit rate.)

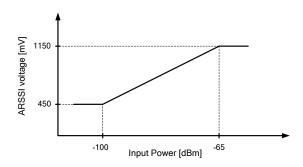


Data Validity Blocks

RSSI

A digital RSSI output is provided to monitor the input signal level. It goes high if the received signal strength exceeds a given preprogrammed level. An analog RSSI signal is also available. The RSSI settling time depends on the external filter capacitor. Pin 15 is used as analog RSSI output. The digital RSSI can be monitored by reading the status register.

Typical Analog ARSSI Voltage vs. RF Input Power



DQD

The operation of the Data Quality Detector is based on counting the spikes on the unfiltered received data. High output signal indicates an operating FSK transmitter within baseband filter bandwidth from the local oscillator. DQD threshold parameter can be set by using the *Data Filter Command* (page 20).

AFC

By using an integrated Automatic Frequency Control (AFC) feature, the receiver can minimize the TX/RX offset in discrete steps, allowing the use of:

- Narrower receiver bandwidth (i.e. increased sensitivity)
- Higher data rate
- · Inexpensive crystals

Crystal Oscillator

The Si4421 has a single-pin crystal oscillator circuit, which provides a 10 MHz reference signal for the PLL. To reduce external parts and simplify design, the crystal load capacitor is internal and programmable. Guidelines for selecting the appropriate crystal can be found later in this datasheet.

The transceiver can supply a clock signal for the microcontroller; so accurate timing is possible without the need for a second crystal.

When the microcontroller turns the crystal oscillator off by clearing the appropriate bit using the *Power Management Command* (page 16), the chip provides a fixed number (192) of further clock pulses ("clock tail") for the microcontroller to let it go to idle or sleep mode. If this clock output is not used, it is

suggested to turn the output buffer off by the *Power Management Command* (page 16).

Low Battery Voltage Detector

The low battery detector circuit monitors the supply voltage and generates an interrupt if it falls below a programmable threshold level. The detector circuit has 50 mV hysteresis.

Wake-Up Timer

The wake-up timer has very low current consumption (1.5 μ A typical) and can be programmed from 1 ms to several days with an accuracy of $\pm 10\%$.

The wake-up timer calibrates itself to the crystal oscillator at every startup. For proper calibration of the wake-up timer the crystal oscillator must be running before the wake-up timer is enabled. The calibration process takes approximately 0.5ms. For the crystal start up time (tsx), see page 12.

Event Handling

In order to minimize current consumption, the transceiver supports different power saving modes. Active mode can be initiated by several wake-up events (negative logical pulse on nINT input, wake-up timer timeout, low supply voltage detection, on-chip FIFO filled up or receiving a request through the serial interface).

If any wake-up event occurs, the wake-up logic generates an interrupt signal, which can be used to wake up the microcontroller, effectively reducing the period the microcontroller has to be active. The source of the interrupt can be read out from the transceiver by the microcontroller through the SDO pin.

Interface and Controller

An SPI compatible serial interface lets the user select the frequency band, center frequency of the synthesizer, and the bandwidth of the baseband signal path. Division ratio for the microcontroller clock, wake-up timer period, and low supply voltage detector threshold are also programmable. Any of these auxiliary functions can be disabled when not needed. All parameters are set to default after power-on; the programmed values are retained during sleep mode. The interface supports the read-out of a status register, providing detailed information about the status of the transceiver and the received data.

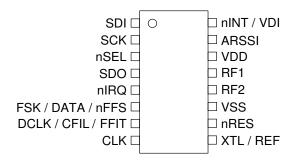
The transmitter block is equipped with two 8-bit wide TX data registers. It is possible to write 8 bits into the register in burst mode and the internal bit rate generator transmits the bits out with the predefined rate. For further details, see the *TX Register Buffered Data Transmission* section (page 29).

It is also possible to store the received data bits into a FIFO register and read them out in a buffered mode.



PACKAGE PIN DEFINITIONS

Pin type key: D=digital, A=analog, S=supply, I=input, O=output, IO=input/output



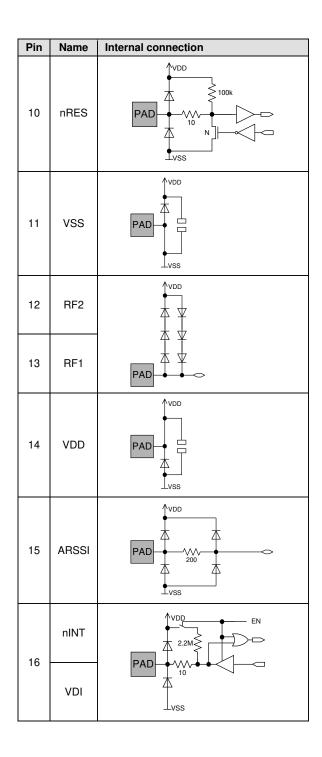
Pin	Name	Туре	Function
1	SDI	DI	Data input of the serial control interface
2	SCK	DI	Clock input of the serial control interface
3	nSEL	DI	Chip select input of the serial control interface (active low)
4	SDO	DO	Serial data output with bus hold
5	nIRQ	DO	Interrupt request output (active low)
	FSK	DI	Transmit FSK data input (internal pull up resistor 133 k)
6	DATA	DO	Received data output (FIFO not used)
Ü	nFFS	DI	FIFO select input (active low). In FIFO mode, when bit <i>ef</i> is set in <i>Configuration Setting Command</i> , page 16 (internal pull up resistor 133 k)
	DLCK	DO	Received data clock output (Digital filter used, FIFO not used)
7	CFIL	AIO	External data filter capacitor connection (Analog filter used)
	FFIT	DO	FIFO interrupt (active high). In FIFO mode, when bit ef is set in Configuration Setting Command
8	CLK	DO	Microcontroller clock output
۵	XTL	AIO	Crystal connection (the other terminal of crystal to VSS) or external reference input
9	6 nFFS DI 7 CFIL AIO FFIT DO 8 CLK DO 3 XTL AIO REF AIO 10 nRES DIO 11 VSS S 12 RF2 AIO	AIO	External reference input. Use 33 pF series coupling capacitor
10	nRES	DIO	Open drain reset output with internal pull-up and input buffer (active low)
11	VSS	S	Ground reference voltage
12	RF2	AIO	RF differential signal input/output
13	RF1	AIO	RF differential signal input/output
14	VDD	S	Positive supply voltage
15	ARSSI	AO	Analog RSSI output
16	nINT	DI	Interrupt input (active low)
10	VDI	DO	Valid data indicator output

Note: The actual mode of the multipurpose pins (pin 6 and 7) is determined by the TX/RX data I/O settings of the transceiver.



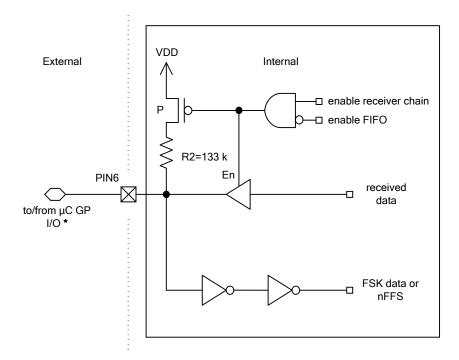
Internal Pin Connections

Pin	Name	Internal connection
1	SDI	↑vdb
2	SCK	PAD 1.5k
3	nSEL	Lvss
4	SDO	PAD 10 EN
5	nIRQ	PAD VSS
	FSK	↑VDD
6	DATA	PAD \$133k
	nFFS	45
	DLCK	↑vDD
7	CFIL	PAD 10 EN
	FFIT	Lvss
8	CLK	PAD No
9	XTL	PAD 2000
	REF	200 A LVSS

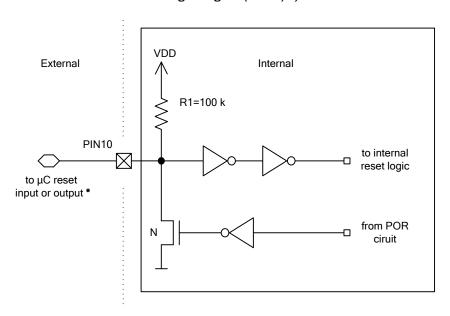




PIN6 Logic Diagram (FSK / DATA / nFFS)



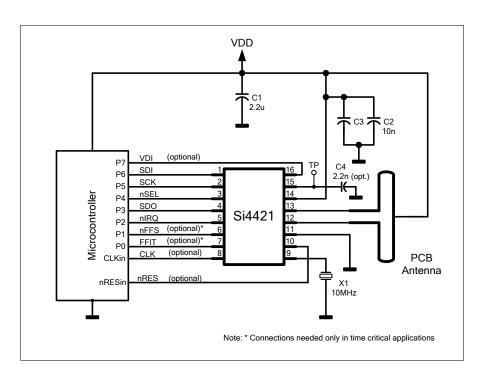
PIN10 Logic Diagram (nRES I/0)



* Note: These pins can be left floating.



Typical Application



Typical application with FIFO usage

Recommended supply decoupling capacitor values

C2 and C3 should be 0603 size ceramic capacitors to achieve the best supply decoupling.

Band [MHz]	C1	C2	C3
433	2.2µF	10nF	220pF
868	2.2µF	10nF	47pF
915	2.2μF	10nF	33pF

Property	C1	C2	C3
SMD size	Α	0603	0603
Dielectric	Tantalum	Ceramic	Ceramic

Pin Function vs. Operation Mode

Mode	Bit setting	Function	Pin 6	Pin 7	
	el = 0 Internal TX data register disabled		TX data input	Naturad	
Transmit	<i>el</i> = 1	Internal TX data register enabled	nFFS input (TX data register can be accessed)	Not used	
Pagaiya	<i>ef</i> = 0	Receiver FIFO disabled	RX data output	RX data clock output	
Receive	<i>ef</i> = 1	Receiver FIFO disabled	nFFS input (RX data FIFO can be accessed)	FFIT output	

The el and ef bits can be found in the Configuration Setting Command on page 16. Bit el enables the internal TX data register. Bit el enables the FIFO mode.



GENERAL DEVICE SPECIFICATIONS

All voltages are referenced to $V_{\mbox{\scriptsize SS}}$, the potential on the ground reference pin VSS.

Absolute Maximum Ratings (non-operating)

Symbol	Parameter	Min	Max	Units
V_{dd}	Positive supply voltage	-0.5	6	V
V _{in}	Voltage on any pin (except RF1 and RF2)	-0.5	V _{dd} +0.5	V
V _{oc}	Voltage on open collector outputs (RF1, RF2)	-0.5	V _{dd} +1.5 (Note 1)	V
I _{in}	Input current into any pin except VDD and VSS	-25	25	mA
ESD	Electrostatic discharge with human body model		1000	V
T _{st}	Storage temperature	-55	125	°C
T _{Id}	Lead temperature (soldering, max 10 s)		260	°C

Recommended Operating Range

Symbol	Parameter	Min	Max	Units
V_{dd}	Positive supply voltage	2.2	3.8	V
V _{oc}	Voltage range on open collector outputs (RF1, RF2)	V _{dd} -1.5 (Note 2)	V _{dd} +1.5	V
T _{op}	Ambient operating temperature	-40	85	°C

Note 1: The voltage on RF1 and RF2 pins can be higher than the actual V_{dd} but cannot exceed 7 V.

Note 2: The actual voltage on RF1 and RF2 pins can be lower than the current V_{dd} but never should go below 1.2 V.



ELECTRICAL SPECIFICATION

Test Conditions: T_{op} = 27 °C; V_{dd} = V_{oc} = 3.3 V

DC Characteristics

Symbol	Parameter	Conditions/Notes	Min	Тур	Max	Units
		433 MHz band		15		
I _{dd_TX_0}	Supply current (TX mode, P _{out} = 0 dBm)	868 MHz band		16		mA
	(1) Cinodo, Fout = 0 deni)	915 MHz band		17		
		433 MHz band		22	26	
I _{dd_TX_PMAX}	Supply current (TX mode, P _{out} = P _{max})	868 MHz band		23	27	mA
	(Tyernodo, Four - Fmax)	915 MHz band		24	5 6 7 2 26 3 27 4 28 1 13 2 14 3 15 .3 1 .5 1.7 .5 3.5 6 1.2 3.75	
		433 MHz band		11	13	
I_{dd_RX}	Supply current (RX mode)	868 MHz band		12	14	mA
		915 MHz band		13	15	
l _{pd}	Standby current (Sleep mode)	All blocks disabled		0.3	1	μΑ
I _{lb}	Low battery voltage detector current consumption			0.5	1.7	μΑ
I _{wt}	Wake-up timer current consumption			1.5	3.5	μΑ
I _x	Idle current	Crystal oscillator on (Note 1)		0.6	1.2	mA
V _{Ib}	Low battery detect threshold	Programmable in 0.1 V steps	2.25		3.75	V
V _{Iba}	Low battery detection accuracy			± 3		%
V _{il}	Digital input low level voltage				$0.3 \cdot V_{dd}$	V
V_{ih}	Digital input high level voltage		0.7·V _{dd}			V
l _{ii}	Digital input current	V _{il} = 0 V	-1		1	μΑ
I _{ih}	Digital input current	$V_{ih} = V_{dd}, \ V_{dd} = 3.8 \ V$	-1		1	μΑ
V _{ol}	Digital output low level	I _{ol} = 2 mA			0.4	V
V _{oh}	Digital output high level	I _{oh} = -2 mA	V _{dd} -0.4			V

Notes are on page 13.



AC Characteristics (PLL parameters)

Symbol	Parameter	Conditions/Notes	Min	Тур	Max	Units
f _{ref}	PLL reference frequency	(Note 2)	9	10	11	MHz
		433 MHz band, 2.5 kHz resolution	430.24		439.75	MHz
f _o	Receiver LO/Transmitter carrier frequency	868 MHz band, 5.0 kHz resolution	860.48		879.51	
		915 MHz band, 7.5 kHz resolution	900.72		11 439.75	
t _{lock}	PLL lock time	Frequency error < 1kHz after 10 MHz step		30		μs
t _{stP}	PLL startup time (Note 10)	With a running crystal oscillator		200	300	μs

AC Characteristics (Receiver)

Symbol	Parameter	Conditions/Notes	Min	Тур	Max	Units
		mode 0		67		
	Receiver bandwidth	mode 1		134		
BW		mode 2		200		Id Ia
DVV		mode 3		270		kHz
		mode 4		340		
		mode 5		400		
BR _{RX}	FSK bit rate (Note 10)	With internal digital filters	0.6		115.2	kbps
BRA _{RX}	FSK bit rate (Note 10)	With analog filter			256	kbps
P_{min}	Receiver Sensitivity	BER 10 ⁻³ , BW=67 kHz, BR=1.2 kbps, 868 MHz Band (Note 3)		-110		dBm
AFC _{range}	AFC locking range	δf _{FSK} : FSK deviation in the received signal		0.8∙δf _{FSK}		
IIP3 _{inh}	Input IP3	In band interferers in high bands (868 MHz, 915 MHz)		-21		dBm
IIP3 _{outh}	Input IP3	Out of band interferers I f-f _o I > 4 MHz		-18		dBm
IIP3 _{inl}	IIP3 (LNA -6 dB gain)	In band interferers in low band (433 MHz)		-15		dBm
IIP3 _{outl}	IIP3 (LNA -6 dB gain)	Out of band interferers I f-f _o I > 4 MHz		-12		dBm
P _{max}	Maximum input power	LNA: high gain	0			dBm
Cin	RF input capacitance			1		pF
RSa	RSSI accuracy			± 6		dB
RS _r	RSSI range			46		dB
RS_ps	RSSI power supply dependency	When input signal level lower than -54 dBm and greater than -100 dBm		+35		mV/V
C _{ARSSI}	Filter capacitor for ARSSI		1			nF
RS _{step}	RSSI programmable level steps			6		dB
RS _{resp}	DRSSI response time	Until the RSSI signal goes high after the input signal exceeds the preprogrammed limit C _{ARRSI} = 4.7 nF		500		μs
P _{sp_rx}	Receiver spurious emission				-60	dBm

Notes are on page 13.



AC Characteristics (Transmitter)

Symbol	Parameter	Conditions/Notes	Min	Тур	Max	Units
l _{out}	Open collector output DC current	Programmable	0.5		6	mA
D	Max. output power delivered to 50	In 433 MHz band		7		I.D.
$\begin{array}{c c} I_{\text{OUT}} & \text{Open collector} \\ \hline P_{\text{max_50}} & \text{Max. output pr} \\ \text{Ohm load oven twork (Note} \\ \hline P_{\text{max_ant}} & \text{Max. EIRP with PCB antenna} \\ \hline P_{\text{out}} & \text{Typical output} \\ \hline P_{\text{sp}} & \text{Spurious emis} \\ \text{If-}f_{\text{sp}}\text{I} > 1 \text{ MHz} \\ \hline P_{\text{harm}} & \text{Harmonic sup} \\ \hline C_{\text{o}} & \text{Output capaciation automatic ante} \\ \hline Q_{\text{o}} & \text{Quality factor capacitance} \\ \hline L_{\text{out}} & \text{Output phase} \\ \hline \end{array}$	Ohm load over a suitable matching network (Note 4)	In 868 MHz / 915 MHz bands		5		dBm
P _{max ant}	Max. EIRP with suitable selected	In 433 MHz band with monopole antenna with matching network (Note 4)		7		dBm
	FOB antenna (Note 6)	In 868 MHz / 915 MHz bands (Note 5)		7		
P _{out}	Typical output power	Selectable in 2.5 dB steps (Note 7)	P _{max} -17.5		P _{max}	dBm
D	Spurious emission f-f _{sp} > 1 MHz	At max power 50 Ohm load (Note 4)			-55	dBc
r _{sp}		With PCB antenna (Note 5)			-60	UBC
Ъ	Harmonic suppression	At max power 50 Ohm load (Note 4)			-35	dBc
□Fharm		With PCB antenna (Note 5)			-42	ubc
C	Output capacitance (set by the	In 433 MHz band	2	2.6	3.2	pF
O ₀	automatic antenna tuning circuit)	In 868 MHz / 915 MHz bands	2.1	2.7	3.3	ρΓ
0	Quality factor of the output	In 433 MHz band	13	15	17	
\mathcal{Q}_0		In 868 MHz / 915 MHz bands	8	10	12	
_	Outrot aleas asias	100 kHz from carrier, in 868 MHz band		-80		dBc/Hz
Lout	Output phase hoise	1 MHz from carrier, in 868 MHz band		-103		GBC/HZ
BR _{TX}	FSK bit rate	Via internal TX data register			172	kbps
BRA _{TX}	FSK bit rate	TX data connected to the FSK input			256	kbps
df _{fsk}	FSK frequency deviation	Programmable in 15 kHz steps	15		240	kHz

AC Characteristics (Turn-on/Turnaround timings)

Symbol	Parameter	Conditions/Notes	Min	Тур	Max	Units
t _{sx}	Crystal oscillator startup time	Default capacitance bank setting, crystal ESR < 50 Ohm (Note 9). Crystal load capacitance = 16 pF.		2	7	ms
$T_{tx_XTAL_ON}$	Transmitter turn-on time	Synthesizer off, crystal oscillator on with 10 MHz step		250		μs
T _{rx_XTAL_ON}	Receiver turn-on time	Synthesizer off, crystal oscillator on with 10 MHz step		250		μs
T _{tx_rx_SYNT_ON}	Transmitter – Receiver turnover time	Synthesizer and crystal oscillator on during TX/RX change with 10 MHz step		150		μs
T _{rx_tx_SYNT_ON}	Receiver – Transmitter turnover time	Synthesizer and crystal oscillator on during RX/TX change with 10 MHz step		150		μs

AC Characteristics (Others)

Symbol	Parameter	Conditions/Notes	Min	Тур	Max	Units
C _{xl}	Crystal load capacitance, see crystal selection guide	Programmable in 0.5 pF steps, tolerance ± 10%	8.5		16	pF
t _{POR}	Internal POR timeout	After V _{dd} has reached 90% of final value (Note 8)			100	ms
t _{PBt}	Wake-up timer clock accuracy	Crystal oscillator must be enabled to ensure proper calibration at the start up. (Note 9)		± 10		%
C _{inD}	Digital input capacitance				2	pF
t _r , t _f	Digital output rise/fall time	15 pF pure capacitive load			10	ns

Notes are on page 13.



- Note 1: Measured with disabled clock output buffer
- **Note 2:** Not using a 10 MHz crystal is allowed but not recommended because all crystal referred timing and frequency parameters will change accordingly
- Note 3: See the BER diagrams in the measurement results section (page 38) for detailed information
- Note 4: See reference design with 50 Ohm Matching Network (page 40) for details
- Note 5: See reference design with Resonant PCB Antenna (BIFA) on page 42 for details
- Note 6: Optimal antenna admittance/impedance:

Si4421	Y _{antenna} [mS]	Z _{antenna} [Ohm]	L _{antenna} [nH]			
433 MHz	2 – j5.9	52 + j152	62			
868 MHz	1.2 - j11.9	7.8 + j83	15.4			
915 MHz	1.49 - j12.8	9 + j77	13.6			

- Note 7: Adjustable in 8 steps
- **Note 8:** During the Power-On Reset period, commands are not accepted by the chip. In case of software reset (see *Wake-Up Timer Command*, page 26) the reset timeout is 0.25ms typical.
- Note 9: The crystal oscillator start up time strongly depends on the capacitance seen by the oscillator. Low capacitance and low ESR crystal is recommended with low parasitic PCB layout design.
- Note 10: By design



CONTROL INTERFACE

Commands to the transmitter are sent serially. Data bits on pin SDI are shifted into the device upon the rising edge of the clock on pin SCK whenever the chip select pin nSEL is low. When the nSEL signal is high, it initializes the serial interface. All commands consist of a command code, followed by a varying number of parameter or data bits. All data are sent MSB first (e.g. bit 15 for a 16-bit command). Bits having no influence (don't care) are indicated with X. Special care must be taken when the microcontroller's built-in hardware serial port is used. If the port cannot be switched to 16-bit mode then a separate I/O line should be used to control the nSEL pin to ensure the low level during the whole duration of the command or a software serial control interface should be implemented. The Power-On Reset (POR) circuit sets default values in all control and command registers.

The receiver will generate an interrupt request (IT) for the microcontroller - by pulling the nIRQ pin low - on the following events:

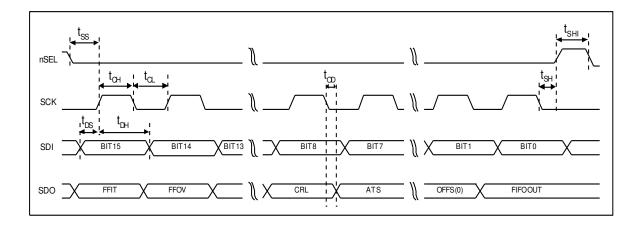
- The TX register is ready to receive the next byte (RGIT)
- The RX FIFO has received the preprogrammed amount of bits (FFIT)
- Power-on reset (POR)
- RX FIFO overflow (FFOV) / TX register underrun (RGUR)
- Wake-up timer timeout (WKUP)
- Negative pulse on the interrupt input pin nINT (EXT)
- Supply voltage below the preprogrammed value is detected (LBD)

FFIT and FFOV are applicable when the RX FIFO is enabled. RGIT and RGUR are applicable only when the TX register is enabled. To identify the source of the IT, the status bits should be read out.

Timing Specification

Symbol	Parameter	Minimum value [ns]
t _{CH}	Clock high time	25
t _{CL}	Clock low time	25
t _{SS}	Select setup time (nSEL falling edge to SCK rising edge)	10
t _{SH}	Select hold time (SCK falling edge to nSEL rising edge)	10
t _{SHI}	Select high time	25
t _{DS}	Data setup time (SDI transition to SCK rising edge)	5
t _{DH}	Data hold time (SCK rising edge to SDI transition)	5
t _{OD}	Data delay time	10

Timing Diagram





Control Commands

	Control Command	Related Parameters/Functions	Related control bits				
1	Configuration Setting Command	Frequency band, crystal oscillator load capacitance, RX FIFO and TX register enable	el, ef, b1 to b0, x3 to x0				
2	Power Management Command	Receiver/Transmitter mode change, synthesizer, crystal oscillator, PA, wake-up timer, clock output enable	er, ebb, et, es, ex, eb, ew, dc				
3	Frequency Setting Command	Frequency of the local oscillator/carrier signal	f11 to f0				
4	Data Rate Command	Bit rate	cs, r6 to r0				
5	Receiver Control Command	Function of pin 16, Valid Data Indicator, baseband bandwidth, LNA gain, digital RSSI threshold	p16, d1 to d0, i2 to i0, g1 to g0, r2 to r0				
6	Data Filter Command	Data filter type, clock recovery parameters	al, ml, s, f2 to f0				
7	FIFO and Reset Mode Command	Data FIFO IT level, FIFO start control, FIFO enable and FIFO fill enable, POR sensitivity	f3 to f0, sp, ff, al, dr				
8	Synchron Pattern Command	Synchron pattern	<i>b7</i> to <i>b0</i>				
9	Receiver FIFO Read Command	RX FIFO read					
10	AFC Command	AFC parameters	a1 to a0, rl1 to rl0, st, fi, oe, en				
11	TX Configuration Control Command	Modulation parameters, output power	mp, m3 to m0, p2 to p0				
12	PLL Setting Command	CLK out buffer speed, dithering, PLL bandwidth	ob1 to ob0, ddit, dly, bw0				
13	Transmitter Register Write Command	TX data register write	<i>t7</i> to <i>t0</i>				
14	Wake-Up Timer Command	Wake-up time period	r4 to r0, m7 to m0				
15	Low Duty-Cycle Command	Enable and set low duty-cycle mode	d6 to d0, en				
16	Low Battery Detector and Microcontroller Clock Divider Command	LBD voltage and microcontroller clock division ratio	d2 to d0, v3 to v0				
17	Status Read Command	Status bit readout					

In general, setting the given bit to one will activate the related function. In the following tables, the POR column shows the default values of the command registers after power-on.

Control Register Default Values

	Control Register	Power-On Reset Value
1	Configuration Setting Command	8008h
2	Power Management Command	8208h
3	Frequency Setting Command	A680h
4	Data Rate Command	C623h
5	Receiver Control Command	9080h
6	Data Filter Command	C22Ch
7	FIFO and Reset Mode Command	CA80h
8	Synchron Pattern Command	CED4h
9	Receiver FIFO Read Command	B000h
10	AFC Command	C4F7h
11	TX Configuration Control Command	9800h
12	PLL Setting Command	CC77h
13	Transmitter Register Write Command	B8AAh
14	Wake-Up Timer Command	E196h
15	Low Duty-Cycle Command	C80Eh
16	Low Battery Detector and Microcontroller Clock Divider Command	C000h
17	Status Read Command	0000h



Description of the Control Commands

1. Configuration Setting Command

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
	1	0	0	0	0	0	0	0	el	ef	b1	b0	x3	x2	x1	x0	8008h

Bit el enables the internal data register.

Bit ef enables the FIFO mode. If ef = 0 then DATA (pin 6) and DCLK (pin 7) are used for data and data clock output.

b1	b0	Frequency Band						
0	0	Reserved						
0	1	1 433						
1	0	868						
1	1	915						

х3	x2	x2	x1	х0	Crystal Load Capacitance [pF]				
0	0	0	0	0	8.5				
0	0	0	0	1	9.0				
0	0	0	1	0	9.5				
0	0	0	1	1	10.0				
1	1	1	1	0	15.5				
1	1	1	1	1	16.0				

2. Power Management Command

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
	1	0	0	0	0	0	1	0	er	ebb	et	es	ex	eb	ew	dc	8208h

Bit	Function of the control bit	Related blocks
er	Enables the whole receiver chain	RF front end, baseband, synthesizer, crystal oscillator
ebb	The receiver baseband circuit can be separately switched on	Baseband
et	Switches on the PLL, the power amplifier, and starts the transmission (If TX register is enabled)	Power amplifier, synthesizer, crystal oscillator
es	Turns on the synthesizer	Synthesizer
ex	Turns on the crystal oscillator	Crystal oscillator
eb	Enables the low battery detector	Low battery detector
ew	Enables the wake-up timer	Wake-up timer
dc	Disables the clock output (pin 8)	Clock output buffer

The ebb, es, and ex bits are provided to optimize the TX to RX or RX to TX turnaround time.

The RF frontend consist of the LNA (low noise amplifier) and the mixer. The synthesizer block has two main components: the VCO and the PLL. The baseband section contains the baseband amplifier, low pass filter, limiter and the I/Q demodulator.

To decrease TX/RX turnaround time, it is possible to leave the baseband section powered on. Switching to RX mode means disabling the PA and enabling the RF frontend. Since the baseband block is already on, the internal startup calibration will not be performed, the turnaround time will be shorter.

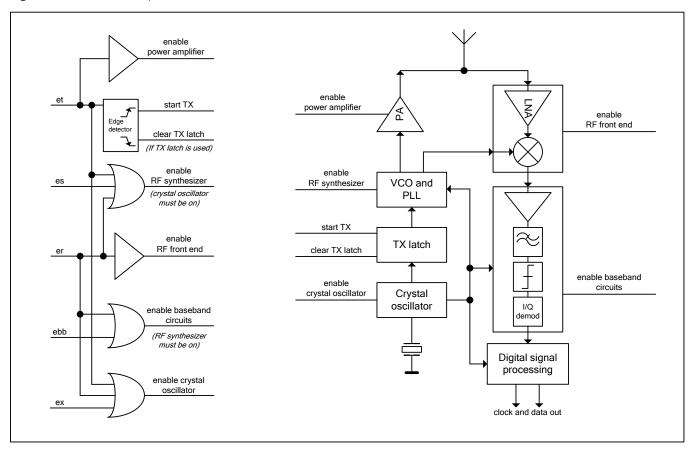
The synthesizer also has an internal startup calibration procedure. If quick RX/TX switching needed it may worth to leave this block on. Enabling the transmitter using the *et* bit will turn on the PA, the synthesizer is already up and running. The power amplifier almost immediately produces TX signal at the output.

The crystal oscillator provides reference signal to the RF synthesizer, the baseband circuits and the digital signal processor part. When the receiver or the transmitter part frequently used, it is advised to leave the oscillator running because the crystal might need a few milliseconds to start. This time mainly depends on the crystal parameters.

It is important to note that leaving blocks unnecessary turned on can increase the current consumption thus decreasing the battery life.



Logic connections between power control bits:



Note:

- If both et and er bits are set the chip goes to receive mode.
- FSK / nFFS input are equipped with internal pull-up resistor. To achieve minimum current consumption do not pull this input to logic low in sleep mode.
- To enable the RF synthesizer, the crystal oscillator must be turned on
- To turn on the baseband circuits, the RF synthesizer (and this way the crystal oscillator) must be enabled.
- Setting the er bit automatically turns on the crystal oscillator, the synthesizer, the baseband circuits and the RF fronted.
- Setting the et bit automatically turns on the crystal oscillator, the synthesizer and the RF power amplifier.

Clock tail feature: When the clock output (pin 8) used to provide clock signal for the microcontroller (*dc* bit is set to 0), it is possible to use the clock tail feature. This means that the crystal oscillator turn off is delayed, after issuing the command (clearing the ex bit) 192 more clock pulses are provided. This ensures that the microcontroller can switch itself to low power consumption mode. In order to use this feature, a *Status Read Command* (page 28) must be issued before the ex bit set to zero. If status read was not performed then the clock output shuts down immediately leaving the microcontroller in unknown state.

Automatic crystal oscillator enable/disable feature: When an interrupt occurs, the crystal oscillator automatically turns on regardless to the setting of the ex bit – to supply clock signal to the microcontroller. After clearing all interrupts by handling them properly (see the *Interrupt Handling* section, page 29) and performing *Status Read Command*, the crystal oscillator is automatically turned off. The clock tail feature provides enough clock pulses for the microcontroller to go to low power mode. Due to this automatic feature, it is not possible to turn off the crystal by clearing the ex bit if any interrupt is active. For example, after power on the POR interrupt must be cleared by a status read then writing zero to the ex bit will put the part into sleep mode. Very important to clear all interrupts before turning the ex bit off because the extra current required by running crystal oscillator can shorten the battery life significantly.

Disabling the clock output (bit dc=1) turns off both the clock tail and the automatic crystal oscillator enable/disable feature, only the ex bit controls the crystal oscillator (supposing that both the er and et bits are cleared), the interrupts have no effect on it.



3. Frequency Setting Command

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
	1	0	1	0	f11	f10	f9	f8	f7	f6	f5	f4	f3	f2	f1	f0	A680h

The 12-bit parameter F (bits f11 to f0) should be in the range of 96 and 3903. When F value sent is out of range, the previous value is kept. The synthesizer center frequency f_0 can be calculated as:

 $f_0 = 10 \cdot C1 \cdot (C2 + F/4000)$ [MHz]

The constants C1 and C2 are determined by the selected band as:

Band [MHz]	C1	C2			
433	1	43			
868	2	43			
915	3	30			

Band	Minimum Frequency	Maximum Frequency	PLL Frequency Step
433 MHz	430.2400 MHz	439.7575 MHz	2.5 kHz
868 MHz	860.4800 MHz	879.5150 MHZ	5.0 kHz
915 MHz	900.7200 MHz	929.2725 MHz	7.5 kHz

4. Data Rate Command

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
	1	1	0	0	0	1	1	0	CS	r6	r5	r4	r3	r2	r1	r0	C623h

The actual bit rate in transmit mode and the expected bit rate of the received data stream in receive mode is determined by the 7-bit parameter R (bits r6 to r0) and bit cs.

 $BR = 10000 / 29 / (R+1) / (1+cs \cdot 7) [kbps]$

In the receiver set R according to the next function:

R= $(10000 / 29 / (1+cs \cdot 7) / BR) - 1$, where BR is the expected bit rate in kbps.

Apart from setting custom values, the standard bit rates from 600 bps to 115.2 kbps can be approximated with small error.

Data rate accuracy requirements:

Clock recovery in slow mode: $\Delta BR/BR < 1/(29 \cdot N_{bit})$

Clock recovery in fast mode: ∆BR/BR < 3/(29 · N_{bit})

BR is the bit rate set in the receiver and \triangle BR is the bit rate difference between the transmitter and the receiver. N_{bit} is the maximum number of consecutive ones or zeros in the data stream. It is recommended for long data packets to include enough 1/0 and 0/1 transitions, and to be careful to use the same division ratio in the receiver and in the transmitter.

5. Receiver Control Command

	Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
_		1	0	0	1	0	p16	d1	d0	i2	i1	i0	g1	g0	r2	r1	r0	9080h

Bit 10 (p16): Pin 16 function select

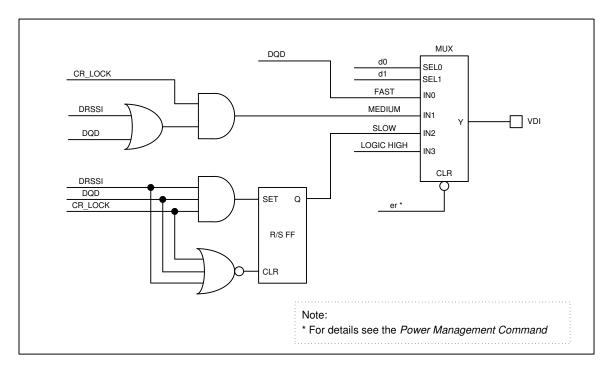
p16	Function of pin 16
0	Interrupt input
1	VDI output



Bits 9-8 (d1 to d0): VDI (valid data indicator) signal response time setting:

d1	d0	Response
0	0	Fast
0	1	Medium
1	0	Slow
1	1	Always on

VDI Logic Diagram:



Slow mode: The VDI signal will go high only if the DRSSI, DQD and the CR_LOCK (Clock Recovery Locked) signals present at the same time. It stays high until any of the abovementioned signals present; it will go low when all the three input signals are low.

Medium mode: The VDI signal will be active when the CR_LOCK signal and either the DRSSI or the DQD signal is high. The valid data indicator will go low when either the CR_LOCK gets inactive or both of the DRSSI or DQD signals go low.

Fast mode: The VDI signal follows the level of the DQD signal.

Always mode: VDI is connected to logic high permanently. It stays always high independently of the receiving parameters.

Bits 7-5 (i2 to i0): Receiver baseband bandwidth (BW) select:

i2	i1	i0	BW [kHz]
0	0	0	Reserved
0	0	1	400
0	1	0	340
0	1	1	270
1	0	0	200
1	0	1	134
1	1	0	67
1	1	1	Reserved

Note: For the optimal bandwidth settings at different data rates see the table on page 38.



Bits 4-3 (g1 to g0): LNA gain select:

g1	g0	Gain relative to maximum [dB]
0	0	0
0	1	-6
1	0	-14
1	1	-20

Bits 2-0 (r2 to r0): RSSI detector threshold:

r2	r1	r0	RSSI _{setth} [dBm]
0	0	0	-103
0	0	1	-97
0	1	0	-91
0	1	1	-85
1	0	0	-79
1	0	1	-73
1	1	0	Reserved
1	1	1	Reserved

The RSSI threshold depends on the LNA gain, the real RSSI threshold can be calculated:

RSSI_{th}=RSSI_{setth}+G_{LNA}

6. Data Filter Command

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
	1	1	0	0	0	0	1	0	al	ml	1	S	1	f2	f1	f0	C22Ch

Bit 7 (al): Clock recovery (CR) auto lock control

1: auto mode: the CR starts in fast mode, after locking it switches to slow mode. Bit 6 (ml) has no effect.

0: manual mode, the clock recovery mode is set by Bit 6 (ml)

Bit 6 (ml): Clock recovery lock control

1: fast mode, fast attack and fast release (4 to 8-bit preamble (1010...) is recommended)

O: slow mode, slow attack and slow release (12 to 16-bit preamble is recommended)

Using the slow mode requires more accurate bit timing (see Data Rate Command, page 18).

Bit 4 (s): Select the type of the data filter:

s	Filter Type							
0	0 Digital filter							
1	Analog RC filter							

Digital: This is a digital realization of an analog RC filter followed by a comparator with hysteresis. The time constant is automatically adjusted to the bit rate defined by the *Data Rate Command* (page 18).

Note: Bit rate cannot exceed 115 kpbs in this mode.

Analog RC filter: The demodulator output is fed to pin 7 over a 10 kOhm resistor. The filter cut-off frequency is set by the external capacitor connected to this pin and VSS.

The table shows the optimal filter capacitor values for different data rates

Data Rate [kbps]	1.2	2.4	4.8	9.6	19.2	38.4	57.6	115.2	256
Filter Capacitor Value	12 nF	8.2 nF	6.8 nF	3.3 nF	1.5 nF	680 pF	270 pF	150 pF	100 pF

Note: If analog RC filter is selected the internal clock recovery circuit and the FIFO cannot be used.



Bits 2-0 (f2 to f0): DQD threshold parameter.

The Data Quality Detector is a digital processing part of the radio, connected to the demodulator - it is an indicator reporting the reception of an FSK modulated RF signal. It will work every time the receiver is on. Setting this parameter defines how clean incoming data stream would be stated as good data (valid FSK signal).

If the internally calculated data quality value exceeds the DQD threshold parameter for five consecutive data bits for both the high and low periods, then the DQD signal goes high.

The DQD parameter in the Data Filter Command should be chosen according to the following rules:

- The DQD parameter can be calculated with the following formula: DQD_{par} = 4 x (deviation TX-RX_{offset}) / bit rate
- It should be larger than 4 because otherwise noise might be treated as a valid FSK signal
- The maximum value is 7.

7. FIFO and Reset Mode Command

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
	1	1	0	0	1	0	1	0	f3	f2	f1	f0	sp	al	ff	dr	CA80h

Bits 7-4 (f3 to f0): FIFO IT level. The FIFO generates IT when the number of received data bits reaches this level.

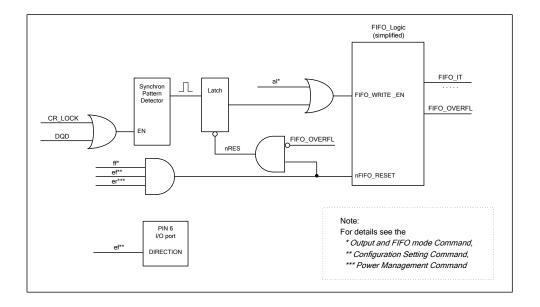
Bit 3 (sp): Select the length of the synchron pattern:

sp	Byte1	Byte0 (POR)	Synchron Pattern (Byte1+Byte0)
0	2Dh	D4h	2DD4h
1	Not used	D4h	D4h

Note: The synchron pattern consists of one or two bytes depending on the *sp* bit. Byte1 is fixed 2Dh, Byte0 can be programmed by the Synchron Pattern Command (page 22).

Bit 2 (al): Set the input of the FIFO fill start condition:

al	FIFO fill start condition
0	Synchron pattern
1	Always fill





Bit 1 (ff): FIFO fill will be enabled after synchron pattern reception. The FIFO fill stops when this bit is cleared.

Bit 0 (dr): Disables the highly sensitive RESET mode.

dr	Reset mode	Reset triggered when
0	Sensitive reset	V _{dd} below 1.6V, V _{dd} glitch greater than 600mV
1	Non-sensitive reset	V _{dd} below 250mV

Note: To restart the synchron pattern recognition, bit 1 (ef, FIFO fill enable) should be cleared and set.

8. Synchron Pattern Command

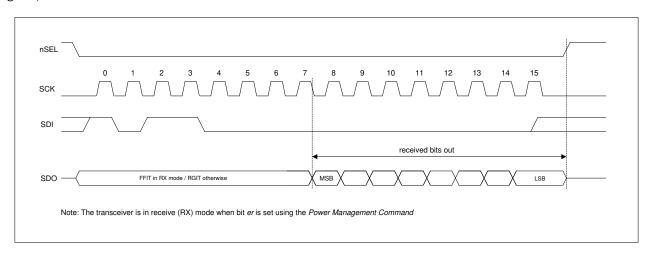
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
	1	1	0	0	1	1	1	0	b7	b6	b5	b4	b3	b2	b1	b0	CED4h

The ByteO of the synchron pattern (see FIFO and Reset Mode command, page 21) can be reprogrammed by B
b7:b0>.

9. Receiver FIFO Read Command

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
	1	0	1	1	0	0	0	0	0	0	0	0	0	0	0	0	B000h

With this command, the controller can read 8 bits from the receiver FIFO. Bit 6 (ef) must be set in Configuration Setting Command (page 16).



Note: During FIFO access f_{SCK} cannot be higher than f_{ref} /4, where f_{ref} is the crystal oscillator frequency. When the duty-cycle of the clock signal is not 50 % the shorter period of the clock pulse width should be at least $2/f_{ref}$.

10. AFC Command

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
	1	1	0	0	0	1	0	0	a1	a0	rl1	rl0	st	fi	oe	en	C4F7h

Bit 7-6 (a1 to a0): Automatic operation mode selector:

a1	a0	Operation mode
0	0	Auto mode off (Strobe is controlled by microcontroller)
0	1	Runs only once after each power-up
1	0	Keep the foffset only during receiving (VDI=high)
1	1	Keep the foffset value independently from the state of the VDI signal



Bit 5-4 (rl1 to rl0): Range limit. Limits the value of the frequency offset register to the next values:

rl1	rI0	Max deviation
0	0	No restriction
0	1	+15 f _{res} to -16 f _{res}
1	0	+7 f _{res} to -8 f _{res}
1	1	+3 f _{res} to -4 f _{res}

433 MHz bands: 2.5 kHz 868 MHz band: 5 kHz 915 MHz band: 7.5 kHz

Bit 3 (st): Strobe edge, when st goes to high, the actual latest calculated frequency error is stored into the offset register of

the AFC block.

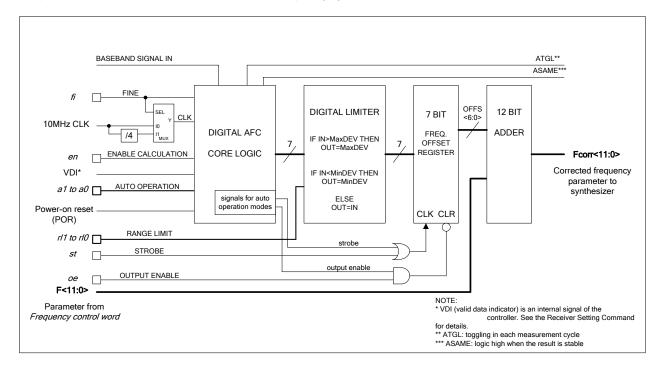
Bit 2 (fi): Switches the circuit to high accuracy (fine) mode. In this case, the processing time is about twice as long, but the

measurement uncertainty is about half.

Bit 1 (oe): Enables the frequency offset register. It allows the addition of the offset register to the frequency control word of

the PLL.

Bit 0 (en): Enables the calculation of the offset frequency by the AFC circuit.



In manual mode, the strobe signal is provided by the microcontroller. One measurement cycle (and strobe) signal can compensate about 50-60% of the actual frequency offset. Two measurement cycles can compensate 80%, and three measurement cycles can compensate 92%. The ATGL bit in the status register can be used to determine when the actual measurement cycle is finished.

In automatic operation mode (no strobe signal is needed from the microcontroller to update the output offset register) the AFC circuit is automatically enabled when the VDI indicates potential incoming signal during the whole measurement cycle and the circuit measures the same result in two subsequent cycles.

Without AFC the transmitter and the receiver needs to be tuned precisely to the same frequency. RX/TX frequency offset can lower the range. The units must be adjusted carefully during production, stable, expensive crystal must be used to avoid drift or the output power needs to be increased to compensate yield loss.

The AFC block will calculate the TX-RX offset. This value will be used to pull the RX synthesizer close to the frequency of the transmitter. The main benefits of the automatic frequency control: cheap crystal can be used, the temperature or aging drift will not cause range loss and no production alignment needed.



There are four operation modes:

- 1. (a1=0, a0=0) Automatic operation of the AFC is off. Strobe bit can be controlled by the microcontroller.
- **2.** (a1=0, a0=1) The circuit measures the frequency offset only once after power up. This way, extended TX-RX distance can be achieved. In the final application, when the user inserts the battery, the circuit measures and compensates for the frequency offset caused by the crystal tolerances. This method allows for the use of cheaper quartz in the application and provides protection against tracking an interferer.
- **3.** (a1=1, a0=0) The frequency offset is calculated automatically and the center frequency is corrected when the VDI is high. The calculated value is dropped when the VDI goes low. To improve the efficiency of the AFC calculation two methods are recommended:
 - **a.** The transmit package should start with a low effective baud rate pattern (i.e.: 00110011) because it is easier to receive. The circuit automatically measures the frequency offset during this initial pattern and changes the receiving frequency accordingly. The further part of the package will be received by the corrected frequency settings.
 - **b.** The transmitter sends the first part of the packet with a step higher deviation than required during normal operation to ease the receiving. After the frequency shift was corrected, the deviation can be reduced.

In both cases (3a and 3b), when the VDI indicates poor receiving conditions (VDI goes low), the output register is automatically cleared. Use this "drop offset" mode when the receiver communicates with more than one transmitter.

4. (a1=1, a0=1) It is similar to mode 3, but suggested to use when a receiver operates with only one transmitter. After a complete measuring cycle, the measured value is kept independently of the state of the VDI signal. When the receiver is paired with only one transmitter, it is possible to use this "keep offset" mode. In this case, the DRSSI limit should be selected carefully to minimize the range hysteresis.

11. TX Configuration Control Command

Ī	Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
		1	0	0	1	1	0	0	mp	m3	m2	m1	m0	0	p2	p1	p0	9800h

Bits 8-4 (mp, m3 to m0): FSK modulation parameters:

The resulting output frequency can be calculated as:

$$f_{out} = f_0 + (-1)^{SIGN} \cdot (M + 1) \cdot (15 \text{ kHz})$$

where:

 f_0 is the channel center frequency (see the Frequency Setting Command)

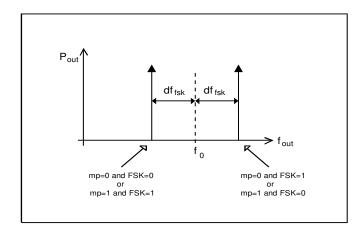
M is the four bit binary number < m3 : m0 > SIGN = (mp) XOR FSK

Note: For the optimal FSK modulation settings at different data rates see the table on page 38.

Bits 2-0 (p2 to p0): Output power:

p2	р1	p0	Relative Output Power [dB]
0	0	0	0
0	0	1	-2.5
0	1	0	-5
0	1	1	-7.5
1	0	0	-10
1	0	1	-12.5
1	1	0	-15
1	1	1	-17.5

Note: The output power given in the table is relative to the maximum available power, which depends on the actual antenna impedance. (See: Antenna Application Note: IA ISM-AN1)



Note: FSK represents the value of the actual data bit.

12. PLL Setting Command

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
	1	1	0	0	1	1	0	0	0	ob1	ob0	1	dly	ddit	1	bw0	CC77h

Bits 6-5 (ob1-ob0): Microcontroller output clock buffer rise and fall time control. The ob1-ob0 bits are changing the output drive current of the CLK pin. Higher current provides faster rise and fall times but can cause interference.

ob1	ob0	Selected µC CLK frequency
1	1	5 or 10 MHz (recommended)
1	0	3.3 MHz
0	Χ	2.5 MHz or less

Note: Needed for optimization of the RF performance. Optimal settings can vary according to the external load capacitance.

Bit 3 (dly): Switches on the delay in the phase detector when this bit is set.

Bit 2 (ddit): When set, disables the dithering in the PLL loop.

Bit 0 (bw0): PLL bandwidth can be set for optimal TX RF performance.

bw0	Max bit rate [kbps]	Phase noise at 1MHz offset [dBc/Hz]						
0	86.2	-107						
1	256	-102						

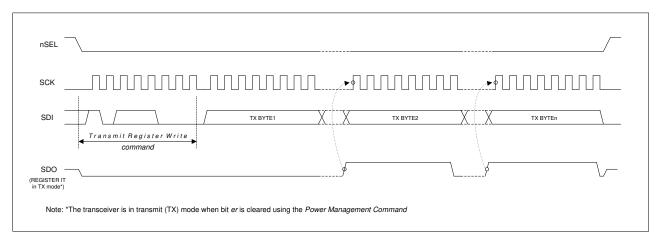
Note: POR default settings of the register were carefully selected to cover almost all typical applications. When changing these values, examine thoroughly the output RF spectrum. For more information, contact Silicon Labs Support.

13. Transmitter Register Write Command

Ī	Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	POR
		1	0	1	1	1	0	0	0	t7	t6	t5	t4	t3	t2	t1	t0	B8AAh

With this command, the controller can write 8 bits (t7 to t0) to the transmitter data register. Bit 7 (el) must be set in Configuration Setting Command (page 16).

Multiple Byte Write with Transmit Register Write Command:



Note: Alternately the transmit register can be directly accessed by nFFS (pin6).

